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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c558-20-ss

Special Microcontroller Features:

- Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- Programmable code protection
- Power saving SLEEP mode
- Selectable oscillator options
- Serial in-circuit programming (via two pins)
- Four user programmable ID locations

Note:	For additional information on enhancements, see Appendix A

CMOS Technology:

- Low power, high speed CMOS EPROM technology
- Fully static design
- Wide operating voltage range
  - 2.5V to 5.5V
- Commercial, Industrial and Extended temperature range
- Low power consumption
  - < 2.0 mA @ 5.0V, 4.0 MHz
  - 15 μA typical 3.0V, 32 kHz
  - < 1.0 μA typical standby current @ 3.0V

Device Differences

Device	Voltage Range	Oscillator
PIC16C554	2.5 - 5.5	**(Note 1)**
PIC16C557	2.5 - 5.5	**(Note 1)**
PIC16C558	2.5 - 5.5	**(Note 1)**

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

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4.2.2.4 PCON Register

The PCON register contains a flag bit to differentiate between a Power-on Reset, an external $\overline{MCLR}$ Reset or WDT Reset. See Section 6.3 and Section 6.4 for detailed RESET operation.

REGISTER 4-4: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	—	$\overline{POR}$	—
bit7							bit0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **$\overline{POR}$**: Power-on Reset status bit
1 = No Power-on Reset occurred
0 = Power-on Reset occurred

bit 0 **Unimplemented:** Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

6.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real-time applications. The PIC16C55X family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection.

These are:

1. OSC selection
2. RESET
3. Power-on Reset (POR)
4. Power-up Timer (PWRT)
5. Oscillator Start-Up Timer (OST)
6. Interrupts
7. Watchdog Timer (WDT)
8. SLEEP
9. Code protection
10. ID Locations
11. In-circuit serial programming™

The PIC16C55X has a Watchdog Timer which is controlled by configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), which is intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in RESET while the power supply stabilizes. With these two functions on-chip, most applications need no external RESET circuitry.

The SLEEP mode is designed to offer a very low current Power-down mode. The user can wake-up from SLEEP through external RESET, Watchdog Timer wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

6.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h – 3FFFh), which can be accessed only during programming.

6.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a pre-packaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with series resonance, or one with parallel resonance.

Figure 6-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 6-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

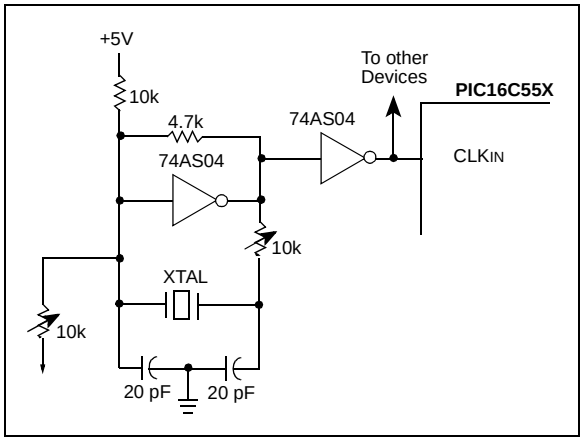
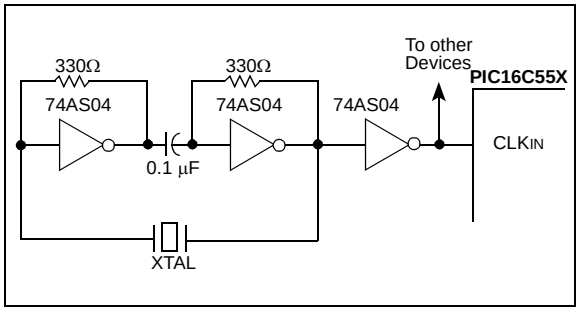


Figure 6-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 6-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



6.2.4 RC OSCILLATOR

For timing insensitive applications the "RC" device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 6-5 shows how the R/C combination is connected to the PIC16C55X. For REXT values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high REXT values (e.g., 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep REXT between 3 kΩ and 100 kΩ.

Although the oscillator will operate with no external capacitor (CEXT = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 6-5: RC OSCILLATOR MODE

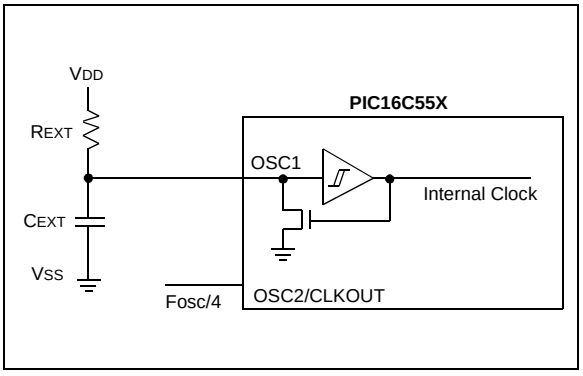


FIGURE 6-7: TIMEOUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1

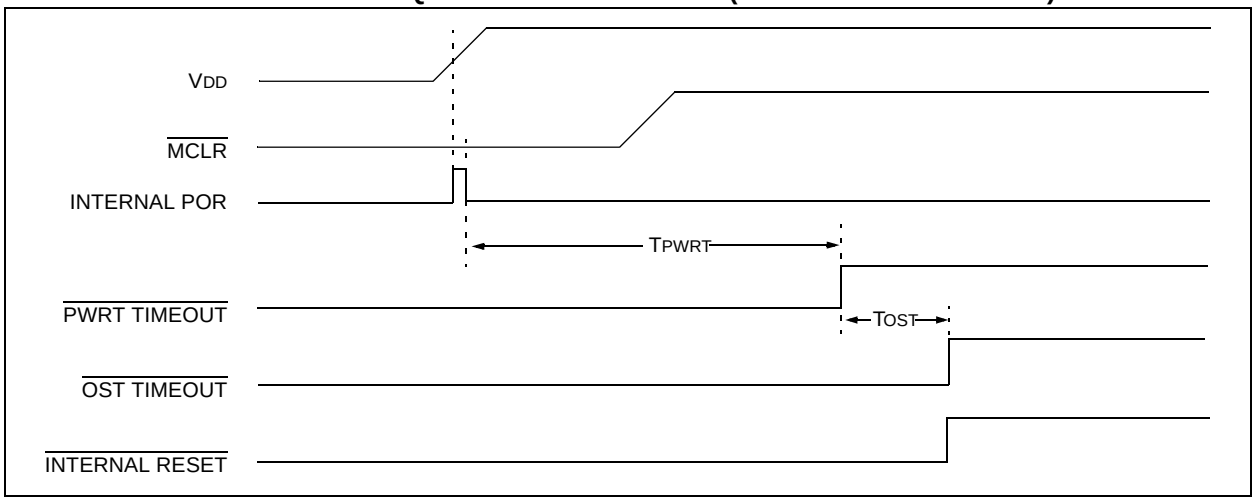


FIGURE 6-8: TIMEOUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2

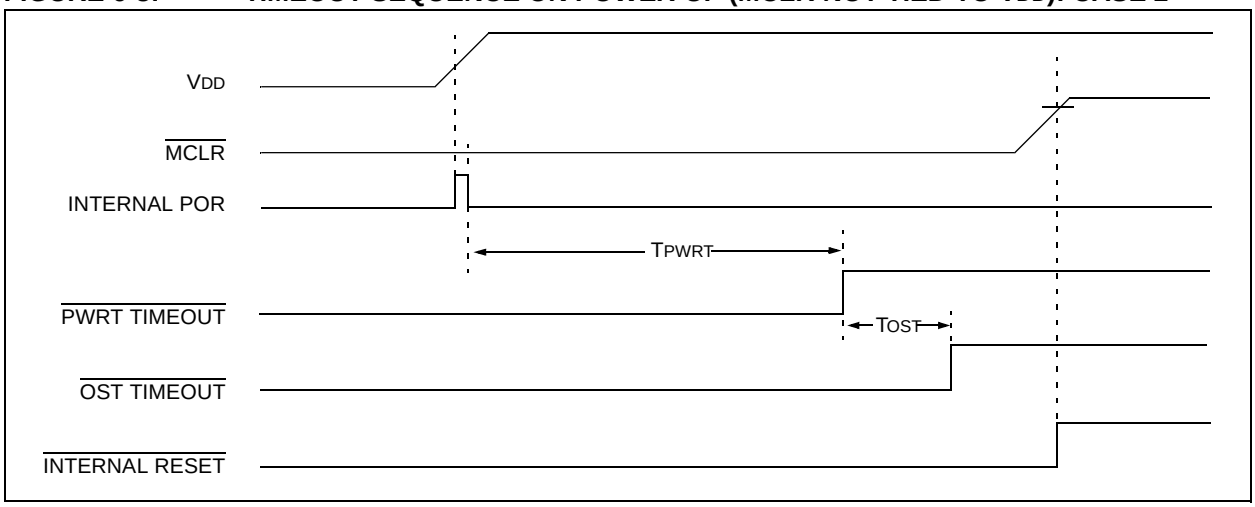


TABLE 8-2: PIC16C55X INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS						
ADDWF	f, d	Add W and f	1	00 0111 dfff ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00 0101 dfff ffff	Z	1,2
CLRF	f	Clear f	1	00 0001 lfff ffff	Z	2
CLRW	-	Clear W	1	00 0001 0000 0011	Z	
COMF	f, d	Complement f	1	00 1001 dfff ffff	Z	1,2
DECF	f, d	Decrement f	1	00 0011 dfff ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00 1011 dfff ffff		1,2,3
INCF	f, d	Increment f	1	00 1010 dfff ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00 1111 dfff ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00 0100 dfff ffff	Z	1,2
MOVF	f, d	Move f	1	00 1000 dfff ffff	Z	1,2
MOVWF	f	Move W to f	1	00 0000 lfff ffff		
NOP	-	No Operation	1	00 0000 0xx0 0000		
RLF	f, d	Rotate Left f through Carry	1	00 1101 dfff ffff	C	1,2
RRF	f, d	Rotate Right f through Carry	1	00 1100 dfff ffff	C	1,2
SUBWF	f, d	Subtract W from f	1	00 0010 dfff ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00 1110 dfff ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00 0110 dfff ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS						
BCF	f, b	Bit Clear f	1	01 00bb bfff ffff		1,2
BSF	f, b	Bit Set f	1	01 01bb bfff ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1(2)	01 10bb bfff ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1(2)	01 11bb bfff ffff		3
LITERAL AND CONTROL OPERATIONS						
ADDLW	k	Add literal and W	1	11 111x kkkk kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11 1001 kkkk kkkk	Z	
CALL	k	Call subroutine	2	10 0kkk kkkk kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00 0000 0110 0100	$\overline{TO}$,$\overline{PD}$	
GOTO	k	Go to address	2	10 1kkk kkkk kkkk		
IORLW	k	Inclusive OR literal with W	1	11 1000 kkkk kkkk	Z	
MOVLW	k	Move literal to W	1	11 00xx kkkk kkkk		
RETFIE	-	Return from interrupt	2	00 0000 0000 1001		
RETLW	k	Return with literal in W	2	11 01xx kkkk kkkk		
RETURN	-	Return from Subroutine	2	00 0000 0000 1000		
SLEEP	-	Go into Standby mode	1	00 0000 0110 0011	$\overline{TO}$,$\overline{PD}$	
SUBLW	k	Subtract W from literal	1	11 110x kkkk kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11 1010 kkkk kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

8.1 Instruction Descriptions

ADDLW **Add Literal and W**

Syntax: [*label*] ADDLW k

Operands: $0 \le k \le 255$

Operation: (W) + k → (W)

Status Affected: C, DC, Z

Encoding:

11	111x	kkkk	kkkk

Description: The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.

Words: 1

Cycles: 1

Example
```
ADDLW   0x15
```
Before Instruction
W = 0x10
After Instruction
W = 0x25

ADDWF **Add W and f**

Syntax: [*label*] ADDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) + (f) → (dest)

Status Affected: C, DC, Z

Encoding:

00	0111	dfff	ffff

Description: Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
ADDWF   FSR,   0
```
Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0xD9
FSR = 0xC2

ANDLW **AND Literal with W**

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. (k) → (W)

Status Affected: Z

Encoding:

11	1001	kkkk	kkkk

Description: The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example
```
ANDLW   0x5F
```
Before Instruction
W = 0xA3
After Instruction
W = 0x03

ANDWF **AND W with f**

Syntax: [*label*] ANDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .AND. (f) → (dest)

Status Affected: Z

Encoding:

00	0101	dfff	ffff

Description: AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
ANDWF   FSR,   1
```
Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0x17
FSR = 0x02

BCF **Bit Clear f**

Syntax: [*label*] BCF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $0 \rightarrow$ (f<b>)

Status Affected: None

Encoding:

01	00bb	bfff	ffff

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Example
```
BCF     FLAG_REG, 7
```
Before Instruction
FLAG_REG = 0xC7
After Instruction
FLAG_REG = 0x47

BSF **Bit Set f**

Syntax: [*label*] BSF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $1 \rightarrow$ (f<b>)

Status Affected: None

Encoding:

01	01bb	bfff	ffff

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Example
```
BSF     FLAG_REG,   7
```
Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

BTFSC **Bit Test, Skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

01	10bb	bfff	ffff

Description: If bit 'b' in register 'f' is '0' then the next instruction is skipped. If bit 'b' is '0' then the next instruction fetched during the current instruction execution is discarded, and a `NOP` is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example
```
HERE    BTFSC   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```
Before Instruction
PC = address `HERE`
After Instruction
if FLAG<1> = 0,
PC = address `TRUE`
if FLAG<1> = 1,
PC = address `FALSE`

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Encoding:

00	0001	0000	0011

Description: W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example
```
CLRW
```
Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0100

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Example
```
CLRWDT
```
Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

COMF **Complement f**

Syntax: [*label*] COMF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: ($\bar{f}$) → (dest)

Status Affected: Z

Encoding:

00	1001	dfff	ffff

Description: The contents of register 'f' are complemented. If 'd' is 0 the result is stored in W. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
COMF    REG1,0
```
Before Instruction
REG1 = 0x13
After Instruction
REG1 = 0x13
W = 0xEC

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: (f) - 1 → (dest)

Status Affected: Z

Encoding:

00	0011	dfff	ffff

Description: Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
DECF    CNT,  1
```
Before Instruction
CNT = 0x01
Z = 0
After Instruction
CNT = 0x00
Z = 1

MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Encoding:

00	1000	dfff	ffff

Description: The contents of register f is moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example
```
MOVF    FSR,   0
```
After Instruction
W = value in FSR register
Z = 1

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 127$

Operation: (W) → (f)

Status Affected: None

Encoding:

00	0000	1fff	ffff

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example
```
MOVWF   OPTION
```
Before Instruction
OPTION = 0xFF
W = 0x4F
After Instruction
OPTION = 0x4F
W = 0x4F

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

00	0000	0xx0	0000

Description: No operation.

Words: 1

Cycles: 1

Example
```
NOP
```

OPTION **Load Option Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

00	0000	0110	0010

Description: The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC MCU products, do not use this instruction.

10.1 DC Characteristics: PIC16C55X-04 (Commercial, Industrial, Extended) PIC16C55X-20 (Commercial, Industrial, Extended) HCS1365-04 (Commercial, Industrial, Extended)

DC Characteristics			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		16LC55X	3.0 2.5	—	5.5 5.5	V	XT and RC osc configuration LP osc configuration
D001 D001A		16C55X	3.0 4.5	— —	5.5 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 6.4, Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 6.4, Power-on Reset for details
	IDD	**Supply Current(2)**					
D010		16LC55X	—	1.4	2.5	mA	XT and RC osc configuration Fosc = 2.0 MHz, VDD = 3.0V, WDT disabled(4)
D010A			—	26	53	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D010		16C55X	—	1.8	3.3	mA	XT and RC osc configuration FOSC = 4 MHz, VDD = 5.5V, WDT disabled(4)
D010A			—	35	70	μA	LP osc configuration, PIC16C55X-04 only FOSC = 32 kHz, VDD = 4.0V, WDT disabled
D013			—	9.0	20	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data is "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins configured as input, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins configured as input and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

FIGURE 10-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

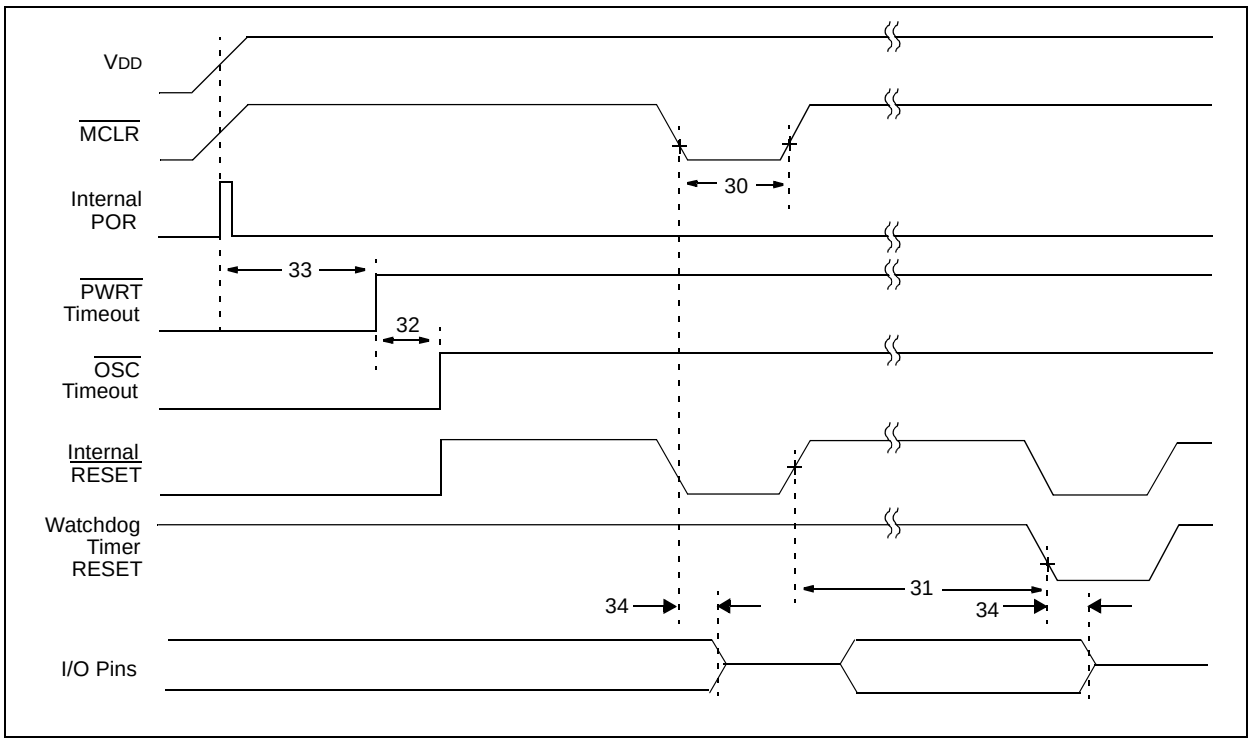


TABLE 10-3: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2000	—	—	ns	-40° to +85°C
31	Twdt	Watchdog Timer Timeout Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5.0V, -40° to +85°C
34	TIOZ	I/O hi-impedance from $\overline{\text{MCLR}}$ low		—	2.0*	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 10-9: TIMER0 CLOCK TIMING

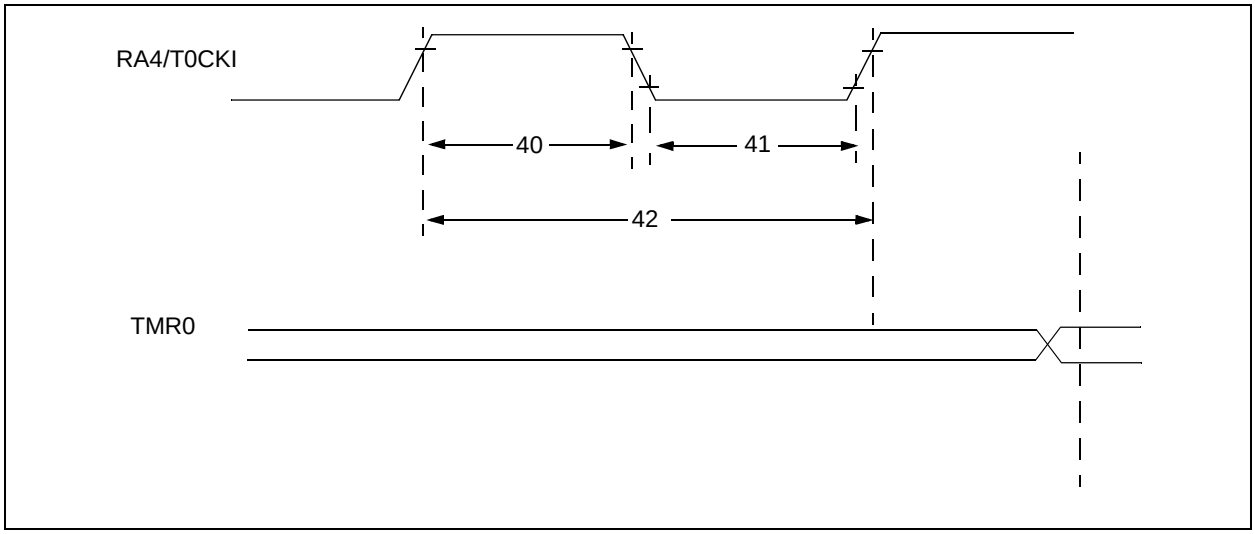


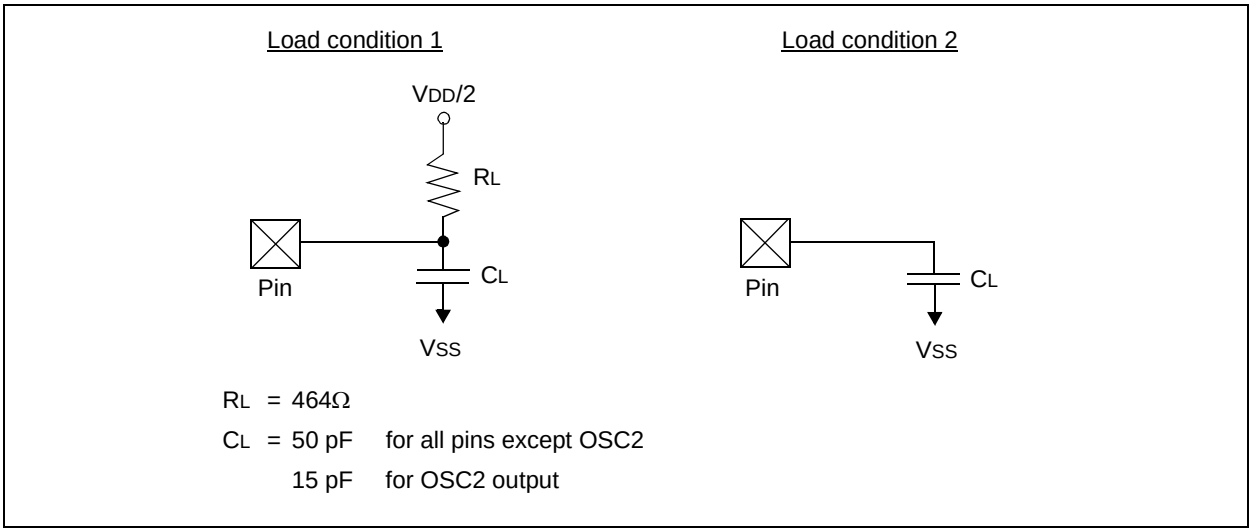
TABLE 10-4: TIMER0 CLOCK REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		$\frac{T_{CY} + 40}{N}$*	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

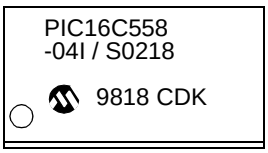
FIGURE 10-10: LOAD CONDITIONS



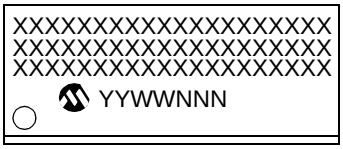
Package Marking Information (Cont'd)

18-Lead SOIC (.300")

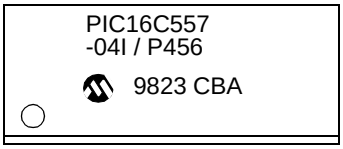
Example



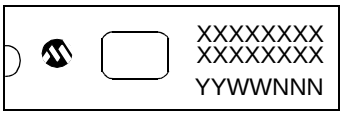
28-Lead SOIC (.300")



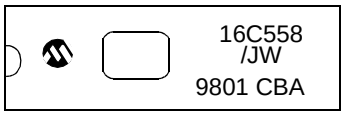
Example



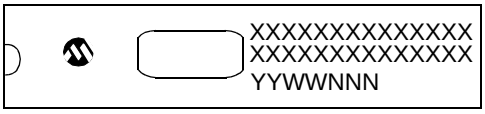
18-Lead CERDIP Windowed



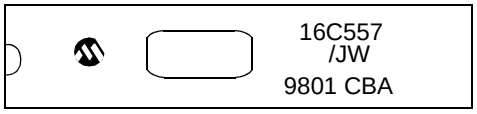
Example



28-Lead CERDIP Windowed

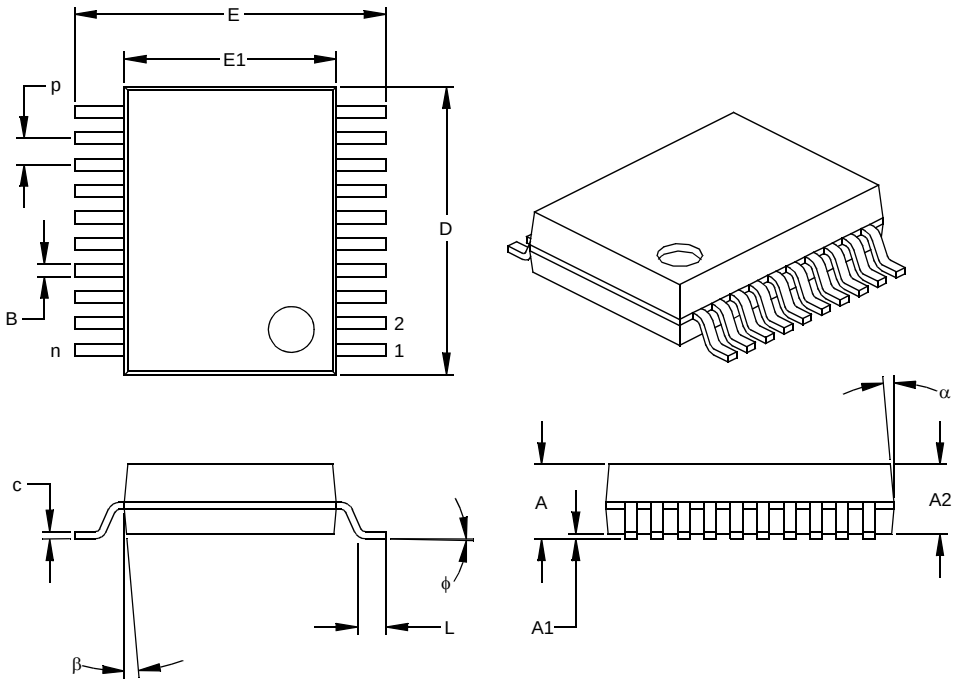


Example



20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ϕ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC17C756: Standard V_{DD} range PIC17C756T: (Tape and Reel) PIC17LC756: Extended V_{DD} range	
Temperature Range	- = 0°C to +70°C I = -40°C to +85°C	
Package	CL = Windowed LCC PT = TQFP L = PLCC	
Pattern	QTP, SQTP, ROM Code (factory specified) or Special Requirements. Blank for OTP and Windowed devices.	

Examples:

a) PIC17C756–16L Commercial Temp., PLCC package, 16 MHz, normal V_{DD} limits

b) PIC17LC756–08/PT Commercial Temp., TQFP package, 8MHz, extended V_{DD} limits

c) PIC17C756–33I/PT Industrial Temp., TQFP package, 33 MHz, normal V_{DD} limits

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)

NOTES:

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